

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	386489	174\$.ccls. or 361\$.ccls. or 428\$.ccls. or 257\$.ccls.	USPAT	OR	OFF	2005/09/30 12:50
L2	3000	L1 and (((Cu or copper)near laminat\$3) or ((Cu or copper) near clad))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/09/30 12:41
L3	2568	L2 and (etch\$3 or fill\$2 or (standoff or (stand off) or (stand-off)))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/09/30 12:42
L4	1923	L2 and ((PCB or (printed near board) or ( circuit near board) or (wiring near board)))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/09/30 12:42
L5	125480	174\$.ccls. or 361\$.ccls.	USPAT	OR	OFF	2005/09/30 12:03
L6	22	174/260-266 and @py>"204"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/09/30 12:08
L7	4	174/260-266 and @py>"2004"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/09/30 12:09
L8	315	174/260-266.ccls. and @py>"2004"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/09/30 12:09
L9	315	174/260-266.ccls. and @py>"2004"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/09/30 12:09
L10	315	174/260-266.ccls. and @py>"2004"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/09/30 12:25
L11	2	"6090474".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/09/30 12:34
L12	18021	(((Cu or copper)near laminat\$3) or ((Cu or copper) near clad))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/09/30 12:41
L13	4518740	(etch\$3 or fill\$2 or (standoff or (stand off) or (stand-off)))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/09/30 12:45

L14	10675	12 and 13	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/09/30 12:43
L15	454273	((PCB or (printed near board) or (circuit near board) or (wiring near board)))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/09/30 12:44
L16	6696	14 and 15	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/09/30 12:43
L17	5493	12 same 13	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/09/30 12:46
L18	1979	17 same 15	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/09/30 12:43
L19	411	1 and 18	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/09/30 12:44
L20	4180576	(fill\$2 or (standoff or (stand off) or (stand-off)))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/09/30 12:45
L21	1066	17 same (via or (through near hole) or throughhole or opening)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/09/30 12:47
L22	454492	21 same 2 15	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/09/30 12:48
L23	32070	1 and 22	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/09/30 12:47
L24	434	21 same 15	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/09/30 12:48
L25	91	24 and 1	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/09/30 12:52
L26	386489	174\$.ccls. or 361\$.ccls. or 428\$.ccls. or 257\$.ccls. or 029\$.ccls.	USPAT	OR	OFF	2005/09/30 12:51

L27	680639	174\$.ccls. or 361\$.ccls. or 428\$. ccls. or 257\$.ccls. or 29\$.ccls.	USPAT	OR	OFF	2005/09/30 12:51
L28	106	24 and 27	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/09/30 12:52

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1163	174/250.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/09/30 15:27
S1	1	("6,454,154").PN.	USPAT; USOCR	OR	OFF	2004/12/07 10:07
S2	0	("L1andsubstrate").PN.	USPAT; USOCR	OR	OFF	2004/12/07 10:08
S3	1	S1 and substrate	USPAT	OR	OFF	2004/12/07 10:21
S4	482923	S1 or substrate	USPAT	OR	OFF	2004/12/07 10:10
S5	0	S1 and standoff	USPAT	OR	OFF	2004/12/07 10:11
S6	22	hole-fill	USPAT	OR	OFF	2004/12/07 11:24
S7	241067	"257" hole-fill	USPAT	OR	OFF	2004/12/07 11:25
S8	126359	"257".clas.	USPAT	OR	OFF	2004/12/07 11:38
S9	318	S8 and "fill hole"	USPAT	OR	OFF	2004/12/08 08:36
S10	4	S9 and tooling	USPAT	OR	OFF	2004/12/07 11:28
S11	1	S9 and standoff	USPAT	OR	OFF	2004/12/07 11:30
S12	556	S8 and standoff	USPAT	OR	OFF	2004/12/07 11:31
S13	238	S12 and hole	USPAT	OR	OFF	2004/12/07 11:32
S14	53	S13 and fill	USPAT	OR	OFF	2004/12/07 11:32
S15	1844	S8 and fixture	USPAT	OR	OFF	2004/12/07 11:39
S16	0	S15 and fill-hole	USPAT	OR	OFF	2004/12/07 11:39
S17	715	S15 and hole	USPAT	OR	OFF	2004/12/07 12:39
S18	3747	174/260-266.ccls.	USPAT	OR	OFF	2004/12/07 12:40
S19	30	S18 and "filling hole" and @py<"2001"	USPAT	OR	OFF	2004/12/07 12:46
S20	274	S18 and apparatus and hole and @py<"2001"	USPAT	OR	OFF	2004/12/07 13:02
S21	1	("5244143").PN.	USPAT; USOCR	OR	OFF	2004/12/07 13:04
S22	1	("5971058").PN.	USPAT; USOCR	OR	OFF	2004/12/07 13:05
S23	1	("6029882").PN.	USPAT; USOCR	OR	OFF	2004/12/07 13:09
S24	1	("5673846").PN.	USPAT; USOCR	OR	OFF	2004/12/07 13:12
S25	1	("5982038").PN.	USPAT; USOCR	OR	OFF	2004/12/07 13:13
S26	1	("6056191").PN.	USPAT; USOCR	OR	OFF	2004/12/07 13:14

S27	1	("5965043").PN.	USPAT; USOCR	OR	OFF	2004/12/07 13:15
S28	1	("5576052").PN.	USPAT; USOCR	OR	OFF	2004/12/07 13:16
S29	1	("5515604").PN.	USPAT; USOCR	OR	OFF	2004/12/07 13:17
S30	1	("4597826").PN.	USPAT; USOCR	OR	OFF	2004/12/07 13:20
S31	1	("6002177").PN.	USPAT; USOCR	OR	OFF	2004/12/07 13:21
S32	1	("5667418").PN.	USPAT; USOCR	OR	OFF	2004/12/07 13:22
S33	0	("257and@py<201and(fill\$hole)").PN.	USPAT; USOCR	OR	OFF	2004/12/07 13:23
S34	0	("257and@py<201and(fill\$hole)").PN.	USPAT; USOCR	OR	OFF	2004/12/07 13:23
S35	126359	"257".clas.	USPAT	OR	OFF	2004/12/07 13:25
S36	27931	S35 and @py<"2001" and (fill hole)	USPAT	OR	OFF	2004/12/07 13:26
S37	174	S35 and @py<"2001" and "fill hole"	USPAT	OR	OFF	2004/12/07 13:27
S38	355902	Injection	USPAT	OR	OFF	2004/12/07 13:46
S39	129823	S38 and (via or hole) and @py<"2001"	USPAT	OR	OFF	2004/12/07 13:47
S40	55138	S39 and fill\$	USPAT	OR	OFF	2004/12/07 13:48
S41	250	S40 and standoff	USPAT	OR	OFF	2004/12/07 14:09
S42	0	S39 and fill4	USPAT	OR	OFF	2004/12/07 14:10
S43	55138	S39 and fill\$	USPAT	OR	OFF	2004/12/07 14:11
S44	55138	S43 and (via or hole)	USPAT	OR	OFF	2004/12/07 14:12
S45	5	S43 and divice	USPAT	OR	OFF	2004/12/07 14:14
S46	12425	S43 and substrate	USPAT	OR	OFF	2004/12/07 14:14
S47	2194	S46 and sold\$	USPAT	OR	OFF	2004/12/07 14:15
S48	160	S47 and through-hol\$	USPAT	OR	OFF	2004/12/07 14:16
S49	1	("5145691").PN.	USPAT; USOCR	OR	OFF	2004/12/07 15:59
S50	1	("5191709").PN.	USPAT; USOCR	OR	OFF	2004/12/07 15:59
S51	126359	"257".clas.	USPAT	OR	OFF	2004/12/08 08:30
S52	27931	S51 and @py<"2001" and (fill hole)	USPAT	OR	OFF	2004/12/08 08:32
S53	14581	S52 and (etched hole-fill)	USPAT	OR	OFF	2004/12/08 08:32
S54	25472	S52 and (etched hole)	USPAT	OR	OFF	2004/12/08 08:32
S55	719385	S54 and feature for fill hole	USPAT	OR	OFF	2004/12/08 08:33
S56	25472	S54 and (feature for fill hole)	USPAT	OR	OFF	2004/12/08 08:34
S57	240805	S54 and [feature for fill hole]	USPAT	OR	OFF	2004/12/08 08:34

S58	231411	S54 and [feature fill hole]	USPAT	OR	OFF	2004/12/08 08:34
S59	231404	S54 and [feature fill via]	USPAT	OR	OFF	2004/12/08 08:35
S60	232068	S54 and [feature fill via]and [copper layer]	USPAT	OR	OFF	2004/12/08 08:35
S61	126359	"257".clas.	USPAT	OR	OFF	2004/12/08 08:37
S62	318	S61 and "fill hole"	USPAT	OR	OFF	2004/12/08 09:24
S63	15	S62 and [etched hole]	USPAT	OR	OFF	2004/12/08 10:35
S64	1	S61 and "fill etched hole"	USPAT	OR	OFF	2004/12/08 09:25
S65	178	S61 and "etched hole"	USPAT	OR	OFF	2004/12/08 09:42
S66	11592	S61 and pin	USPAT	OR	OFF	2004/12/08 09:43
S67	0	S66 and fill-holl	USPAT	OR	OFF	2004/12/08 09:43
S68	4856	S66 and hole	USPAT	OR	OFF	2004/12/08 09:44
S69	1916	S66 and fill	USPAT	OR	OFF	2004/12/08 09:44
S70	3321	S66 and etched	USPAT	OR	OFF	2004/12/08 09:45
S71	792	S69 and etched	USPAT	OR	OFF	2004/12/08 09:45
S72	518	S71 and via	USPAT	OR	OFF	2004/12/08 09:49
S73	0	S71 and via and coppeer	USPAT	OR	OFF	2004/12/08 09:49
S74	304	S71 and via and copper	USPAT	OR	OFF	2004/12/08 09:59
S75	154	S71 and via and copper and @py<"2001"	USPAT	OR	OFF	2004/12/08 09:59
S76	15	S61 and [etched hole]	USPAT	OR	OFF	2004/12/08 10:37
S77	6638906	S61 and [etched hole]and @py<"2001"	USPAT	OR	OFF	2004/12/08 10:39
S78	15	S61 and [etched hole]	USPAT	OR	OFF	2004/12/08 10:43
S79	388	etched adj hole	USPAT	OR	OFF	2004/12/08 10:44
S80	0	("20030215568.pn.").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	OFF	2005/07/12 18:07
S81	2	"20030215568".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/07/12 18:07
S82	2	"6139904".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/07/13 11:28
S83	13	174/260-266 and @py>"2001"	USPAT	OR	OFF	2005/07/13 11:32
S84	1104	174/260-266.ccls. and @py>"2001"	USPAT	OR	OFF	2005/07/13 11:35
S85	39	S84 and (stand-off or standoff)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/07/13 11:36

S86	2294	257/774-779.ccls. and @py>"2001"	USPAT	OR	OFF	2005/07/13 11:35
S87	68	S86 and (stand-off or standoff)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/07/13 11:37
S88	1	"20030215568".pn.	USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2005/07/13 16:53
S89	2	"6134772".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/07/13 16:54
S90	386489	174\$.ccls. or 361\$.ccls. or 428\$. ccls. or 257\$.ccls.	USPAT	OR	OFF	2005/09/30 12:03
S91	3000	S90 and (((Cu or copper)near laminat\$3) or ((Cu or copper) near clad))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/09/30 11:57
S92	2568	S91 and (etch\$3 or fill\$2 or (standoff or (stand off) or (stand-off)))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/09/30 12:02
S93	1923	S91 and ((PCB or (printed near board) or ( circuit near board) or (wiring near board)))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/09/30 12:03
S94	125480	174\$.ccls. or 361\$.ccls.	USPAT	OR	OFF	2005/09/30 12:03